

NOTES:

1 MATERIAL:

- 1-1 TERMINAL : BERYLLIUM COPPER, THICKNESS 0.20MM
- 1-2 HOUSING : HIGH TEMPERATURE THERMAL PLASTIC
- 1-3 FITTING NAIL: BRASS, THICKNESS 0.20MM

2 FINISH: 2-1 TERMINAL :

- 50~200μm NICKEL UNDER PLATED
- 30μm MIN GOLD PLATING ON CONTACT AREA
- 3μm MIN GOLD FLASH ON SOLDERING AREA

2-2 FITTING NAIL :

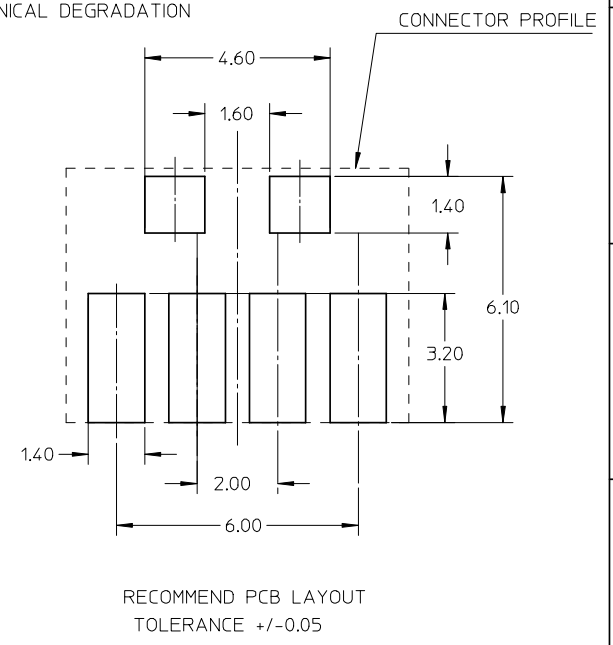
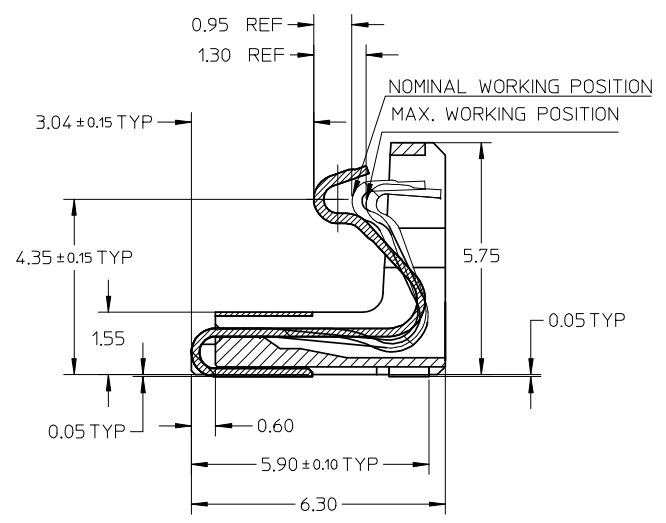
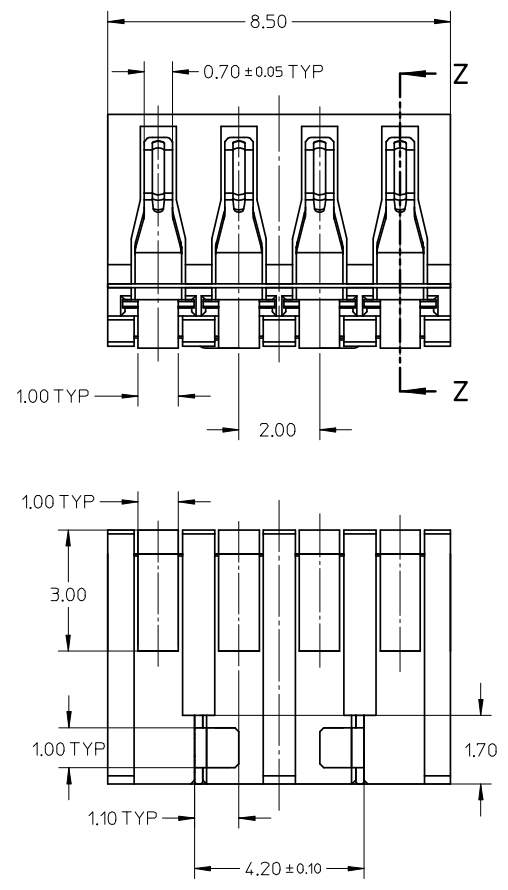
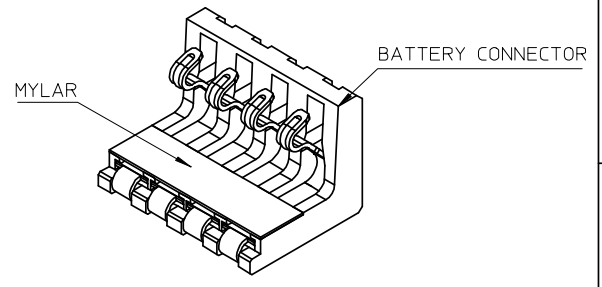
- 50~200μm NICKEL UNDER PLATED
- 100~200μm TIN PLATED ON SOLDERING AREA

3 MECHANICAL SPECIFICATION

NORMAL FORCE: 75g MIN. AT 0.65mm DEFLECTION.
135±25g AT NOMINAL WORKING POSITION.
200g MAX. AT 1.25mm DEFLECTION.

MATING CYCLES : 10,000 TIMES WITHOUT ELECTRICAL OR MECHANICAL DEGRADATION

4. COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV 2000/53/EC



SECTION Z-Z

RELEASED EC NO: SH2008-0435 DRWN: MSH CHKD: YLZHU APPR: HWANG 2008/04/09 2008/04/11 2008/04/14	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION		
	▽=0 ∠=0	mm	INCH	MM ONLY		10:1	METRIC			
		4 PLACES	± ---	± ---	DRAWN BY	DATE	TITLE			
		3 PLACES	± ---	± ---	MSH1	2007/01/11	2.0 MM PITCH 4 PINS BATTERY CONN SALES DRAWING			
	2 PLACES	± 0.10	± ---	CHECKED BY	DATE	MOLEX INCORPORATED				
	1 PLACE	± 0.15	± ---	YLZHU	2008/2/28	DOCUMENT NO.				
		ANGULAR ± 3 °		APPROVED BY	DATE	SD-47575-001		SHEET NO.		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		HWANG	2008/2/28	475750001		1 OF 1		
				MATERIAL NO.		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
				SIZE	A3					